

April 2nd- Time	Sunday-Track 1 – Silicon Modes-REGENCY MAIN	Sunday-Track 2 - Integrated-REGENCY 1		
8:30-10:00am	1-1 Fundamental FEOL Reliability: Defect Generation in Gate Dielectrics to Induce Dielectric Breakdown and Device Degradation <a href="#">Kenji Okada - TowerJazz Panasonic Semiconductor</a>	2-1 Compound Semiconductor Reliability 101 <a href="#">Bill Roesch - Qorvo</a>		
10:00-10:30am	Break			
10:30-noon	1-2 Interconnect Reliability Fundamentals <a href="#">Zsolt Tokei (IMEC)</a>	2-2 VLSI Design Methodology and Design Verification for Reliability <a href="#">Michael Zaslavsky and Tim Turner - The Reliability Simulation Group</a>		
noon-1:30pm	Lunch			
1:30-3:00pm	1-3 Electromigration 101 <a href="#">Cathy Christiansen - Global Foundries</a>	2-3 NAND Flash Memory Reliability <a href="#">Hanmant Belgal and Ivan Kalastirsky - Intel</a>		
3:00-3:30pm	Break			
3:30-5:00pm	1-4 Chip Package Interaction (CPI) and its Impacts on Reliability <a href="#">CS Premachandran - Global Foundries</a>	2-4 Challenges for Failure Analysis - Automotive and More-Than-Moore <a href="#">Ulrike Ganesh - Bosch</a>		
April 3rd-Time	Monday-Track 1 - Advanced Si&Pkg-REGENCY MAIN	Monday-Track 2 - Automotive & IOT-REGENCY 1	Monday-Track 3 - Integrated-BIG SUR	Monday Track 4 - Circuit & System-REGENCY IV
8:00-9:30am	3-1 1. Recent Advances in Negative Bias Temperature Instability (NBTI) in HKMG p-MOSFETs and 2. The Emerging Challenge of Self-heating In Modern FINFET, ETSOI, and Gate-All-Around III-V Transistors: A Transistor to Tablet Perspective <a href="#">1. Souvik Mahapatra (IIT, Bombay) and 2. Muhammad Ashraf Alam (Purdue)</a>	4-1 he automotive transformation – cost, time-to-market, reliability and security driven design optimization from application down to semiconductor technology <a href="#">Andreas Aal - Volkswagen AG</a>	5-1 AlGaN /GaN Power Device Reliability <a href="#">Peter Moens - ON semiconductor</a>	6-1 System Telemetry for Reliability Engineering <a href="#">Rob Kwasnick - Intel</a>
9:30-10:00am	Break			
10:00-11:30am	3-2 Advanced MOL and BEOL Reliability <a href="#">Shou Chung Lee - TSMC</a>	4-2 Introduction to Automotive Functional Safety - History, Trends, and Relation to Reliability <a href="#">Karl Greb - NVIDIA</a>	5-2 Phase Change Memory: From Basic Technology to System Aspects and New Applications <a href="#">Haris Pozidis - IBM</a>	6-2 System Reliability <a href="#">Geny Gao - PHD</a>
11:30am-12:30pm	Lunch			
12:30-2:00pm	3-4 Advanced Packaging and 3D Reliability <a href="#">C. Raman Kothandaraman - IBM</a>	4-3 Juggling Knowledge Based and Standards Based Qualification <a href="#">Bob Knoell - Automotive Electronics Council &amp; NXP</a>	5-3 Spint Torque MRAM <a href="#">Daniel C. Worledge - IBM</a>	6-3 Considerations for In-Field Fault Tolerance, Self-Healing, Detection & Recovery Techniques <a href="#">Arijit Biswas - Intel</a>
2:00-2:30pm	Break			
2:30-5:00pm	Year In Review			